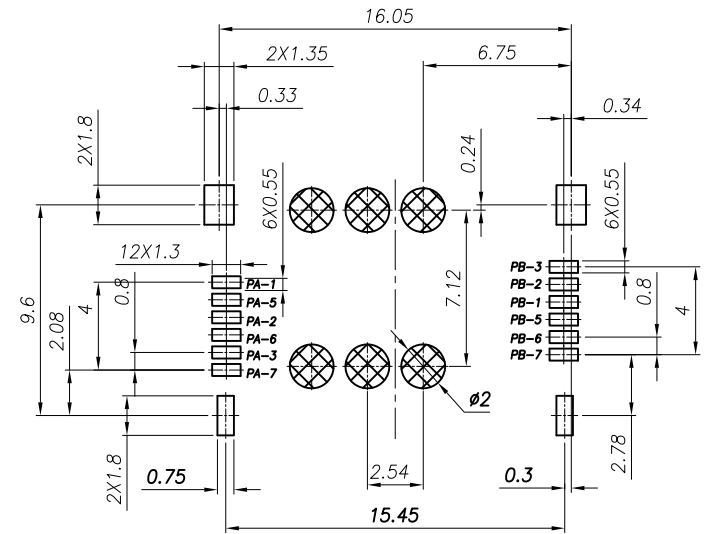


| SIM CARD PIN NO. | PIN NO. |
|------------------|---------|
| P1-A/B | VCC |
| P2-A/B | RST |
| P3-A/B | CLK |
| P5-A/B | GND |
| P6-A/B | VPP |
| P7-A/B | I/O |

| REV. | ECN NO OR DESCRIPTION | REVISED | DATE |
|------|-----------------------|---------|------------|
| ▽ | PROPOSE ONLY | ALLEN | 2015.03.28 |

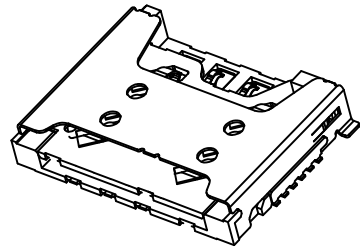
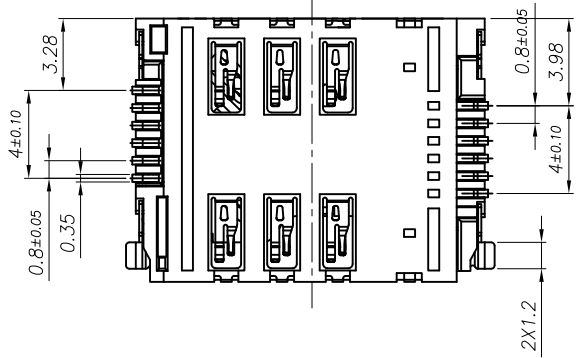
PATTERN PROHIBITION AREA



NOTE:

- MATERIAL:
HOUSING: THERMOPLASTIC, BLACK, UL 94V-0
CONTACT: COPPER ALLOY.
SHELL: STAINLESS STEEL.
- FINISH:
CONTACT: GOLD PLATING 1u"Min., SOLDER AREA 100u" TIN PLATED OVER NICKEL
- SPECIFICATION:
CONTACT RESISTANCE: 80mΩ MAX.
INSULATION RESISTANCE: 1000MΩ MIN.
DIELECTRIC WITHSTANDING VOLTAGE: 500V AC MIN FOR 1 MINUTE.
DURABILITY: 5000 CYCLES.
- PART No.:
S 0 DL - 28 00 12- 10 G
S: SIM CON. G: gold flash
0: WITHOUT POST 10: Product Order
DL: DUAL TYPE. Pin NO. 12=12Pin
28: HEIGHT 2.8mm 00=ON PCB

RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES: ±0.05



| | | | | |
|-----|----------------|------|------------------|----------------|
| ③ | TERMINAL | 12 | C5210-EH, T=0.12 | Au 5u" PLATING |
| ② | BASE INSULATOR | 1 | LCP+GF30% | BLACK |
| ① | SHELL | 1 | SUS304-1, T=0.15 | AU/Ni PLATING |
| NO. | PART NAME | Q'TY | DESCRIPTION | NOTE |

| UNLESS OTHERWISE SPECIFIED TOLERANCES | | 深圳市顺宏康科技有限公司 | | | |
|---------------------------------------|----------|---------------|----------------------------------|--------------------------|--------------|
| DECIMALS: | ANGLES: | TITLE | DUAL Micro SIM 2 in 1 Card Conn. | | |
| x :±0.5 | X :±2° | DWN | ALLEN | PART NO. SODL-280012-10G | |
| X.X :±0.20 | X.X :±1° | CHKD | KEVIN | SCALE: 1:1 | UNIT: mm |
| X.XX :±0.10 | | APVD | ERIC.W | SIZE: A3 | SHEET: 10F 1 |
| | | CUSTOMER COPY | | | |